



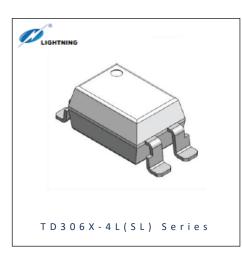
PRODUCT DATASHEET



- DC Input Photo Coupler
- Zero-Cross TRIAC

TD306X-4L(SL)(T1)-GV





APPLICATIONS:

- Solenoid/valve controls •
- Lighting controls
- Motor controls •
- **Temperature controls** .
- Static AC power switches
- Solid state relays •
- Interfacing microprocessors to 115 • to 240VAC peripherals

TD306X-4L(SL) Series

DESCRIPTION:



The TDTD306X-4L(SL) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo TRIAC in a plastic DIP4 package with SMD4 Low Profile lead forming option.

With the robust coplanar double mold structure, TD306X-4L(SL) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with zero-cross photo TRIAC output
- Operating temperature range -40°C to +100°C
- **REACH & RoHS compliance; Halogen free**
- MSL class 1
- **Regulatory Approvals:**
 - UL UL1577 0
 - VDE EN60747-5-5 (VDE0884-5) 0
 - 0 CQC - GB4943.1, GB8898

• **IR IR**

cUL - CSA Component Acceptance Service Notice 5A 0

Packing: T1/T2: 1500pcs/reel; T3/T4: 1000pcs/reel CQC Partner with: WLIGHTNING



Naming Information:

| TD306 X - 4L (SL) (T1) - G V | | | | |
|------------------------------|--|--|--|--|
| TD306 | Part Number | | | |
| × | Selection: LED Trigger Current (X=1~3) | | | |
| 4L | DIP4 Based Package | | | |
| SL | Lead Form Option: SMD4 Low Profile | | | |
| T1 | Selection: Tape and Reel Option (T1(default)/T2/T3/T4) | | | |
| G | Green Option | | | |
| V | VDE Option | | | |

Ordering Information:

| TD306 <u>X</u> -4L(SL)(T1)-GV | | | | | | |
|-------------------------------|---|--------|------|------|----------------|----------------------|
| | <u>X</u> = Selection: LED Trigger Current (X=1~3) | | | | | |
| Part Number | Symbol | Values | | Unit | Test Condition | |
| | Symbol | Min. | Тур. | Max. | onnt | rest condition |
| TD3061-4L(SL)(T1)-GV | | | | 15 | | 100m 1 |
| TD3062-4L(SL)(T1)-GV | I _{FT} | | | 10 | mA | I™=100mA Terminal |
| TD3063-4L(SL)(T1)-GV | | | | 5 | | Voltage=3V |

| Version No. | Original Release Date |
|-------------|-----------------------|
| Rev: A00 | 05/09/2024 |



Image: PIN Definition 1 Anode 2 Cathode 3 Terminal 4 Terminal

Schematic Diagram:

Marking Information:

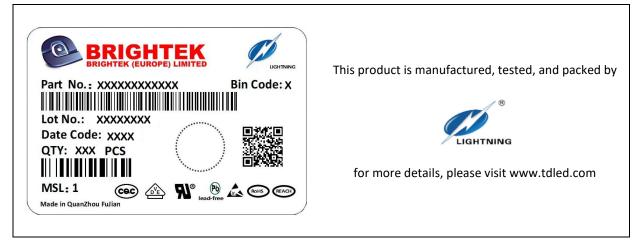
TD

30XX

VYAWW

| Marking Definition | | |
|--------------------|--------------------|--|
| TD | Manufacturer Code | |
| 306X | Part Number & Rank | |
| v | VDE Applicable | |
| Y | Fiscal Year | |
| А | Manufacturing Code | |
| ww | Work Week | |

Labelling Information:





Absolute Maximum Ratings:

| Parameter | Symbol | Ratings | Unit | | | |
|---|------------------|--------------------|------|--|--|--|
| INPUT | | | | | | |
| Forward Current | IF | 60 | mA | | | |
| Reverse Voltage | VR | 6 | V | | | |
| Junction Temperature | Tj | 125 | °C | | | |
| Input Power Dissipation | Pı | 100 | mW | | | |
| | OUTPUT | | | | | |
| Off-State Output Terminal Voltage | V _{DRM} | 600 | V | | | |
| Peak Repetitive Surge Current PW=100μs, 120pps | Ітѕм | 1 | А | | | |
| On-State RMS Current | It(rms) | 100 | mA | | | |
| Junction Temperature | Tj | 125 | °C | | | |
| Output Power Dissipation | Po | 300 | mW | | | |
| COMMON | | | | | | |
| Total Power Dissipation | P _{tot} | 400 | mW | | | |
| Isolation Voltage | Viso | 5000 ^{*1} | Vrms | | | |
| Operating Temperature | Topr | -40~+100 | °C | | | |
| Storage Temperature | T _{stg} | -55~+125 | °C | | | |
| Soldering Temperature | T _{sol} | 260 *2 | °C | | | |

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

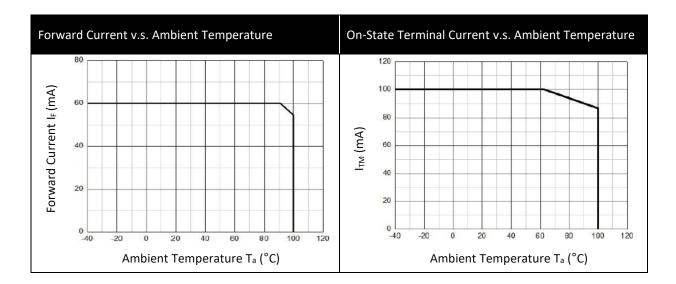
| Electrical Op | otical Characteristics | at T _a =25°C: |
|---------------|------------------------|--------------------------|
|---------------|------------------------|--------------------------|

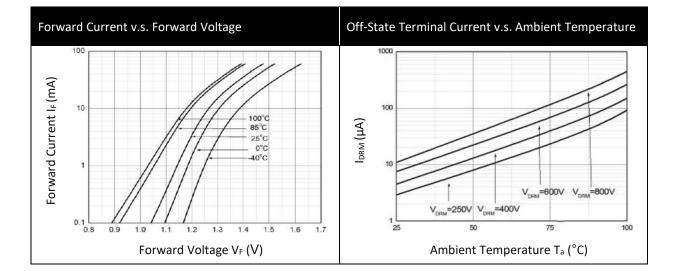
| Paramete | er | Symbol | Min. | Values Typ. | Max. | Unit | Test Condition |
|--|--------------|-------------------|------------|----------------|-------------------|------|---|
| INPUT | | | | | | | |
| Forward Voltage | | V _F | | 1.24 | 1.4 | v | I _F =10mA |
| Reverse Current | | I _R | | | 10 | μΑ | V _R =6V |
| Input Capacitance | | CIN | | 8.5 | 250 | pF | V=0, f=1kHz |
| | | 1 | OUTPL | JT | 1 | 1 | |
| Peak Off-State Curre Either Direction | nt | Idrm | | | 500 ^{*1} | nA | V_{DRM} =Rated V_{DRM} I _F =0 |
| Peak Off-State Voltag | ge | V _{TM} | | 1.59 | 2.5 | v | I _{TM} =100mA |
| Critical Rate of Rise of Voltage | of Off-State | dV/dt | 1000 | | | V/µs | V _{PEAK} =400V I _F =0 |
| | | TRAN | NSFER CHAR | ACTERISTICS | | | |
| | TD3061-4L | | | | 15 | | I™=100mA Terminal |
| LED Trigger Current | TD3062-4L | IFT | | | 10 | mA | |
| | TD3063-4L | | | | 5 | | Voltage=3V |
| Holding Current | | Ін | | 237 | | μA | |
| Isolation Resistance | | R _{ISO} | 10^12 | 10^14 | | Ω | DC=500V, 40~60% R.H. |
| Floating Capacitance | | Сю | | 0.4 | 1 | pF | V=0, f=1MHz |
| ZERO-CROSSING CHARACTERISTICS | | | | | | | |
| Inhibit Voltage | | VINH | | | 20 | V | IF=Rated IFT |
| Leakage in Inhibited | State | I _{DRM2} | | | 500 | μΑ | IF=Rated IFT VDRM=Rated VDRM |

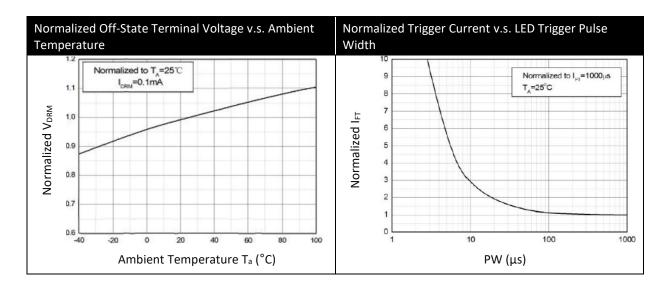
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

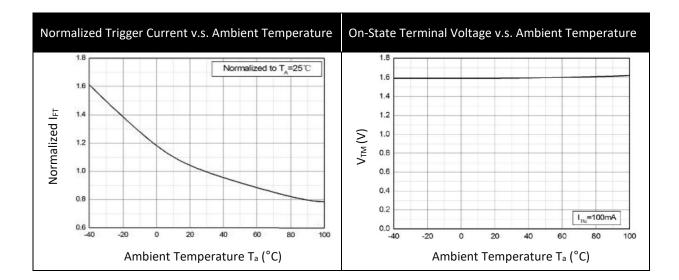


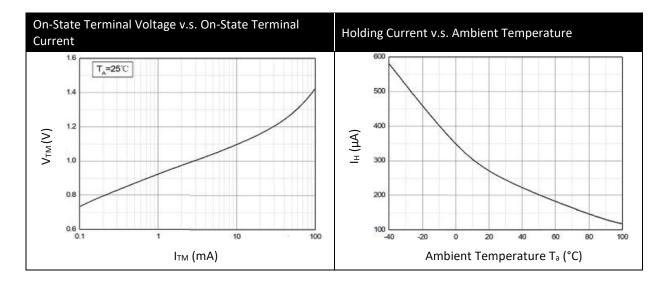


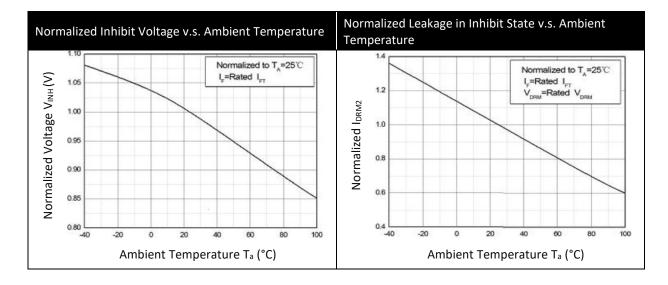




CHARACTERISTIC CURVES:

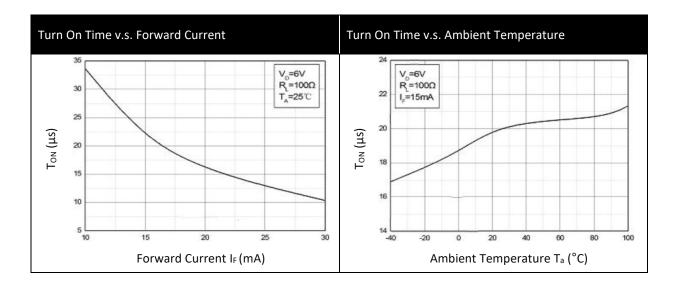






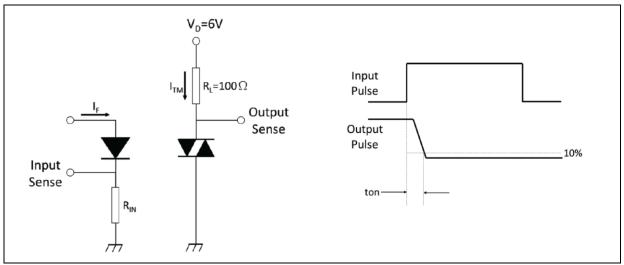


CHARACTERISTIC CURVES:



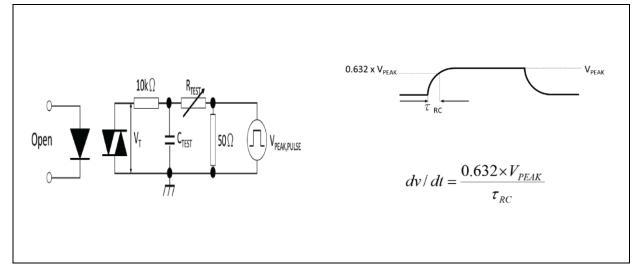


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

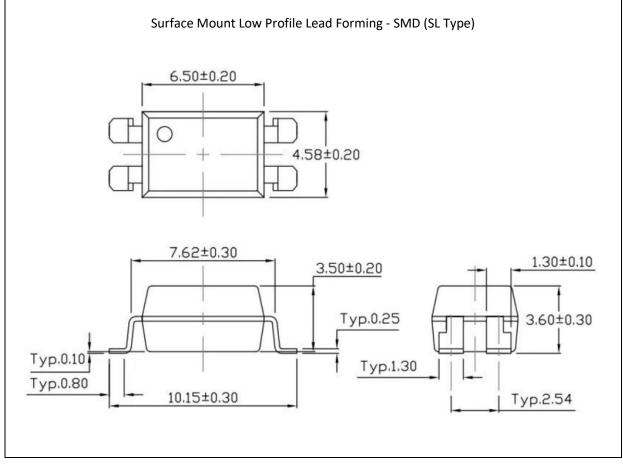
Test Circuit and Waveforms of dV/dt:





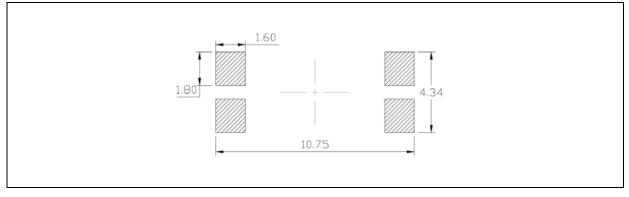
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

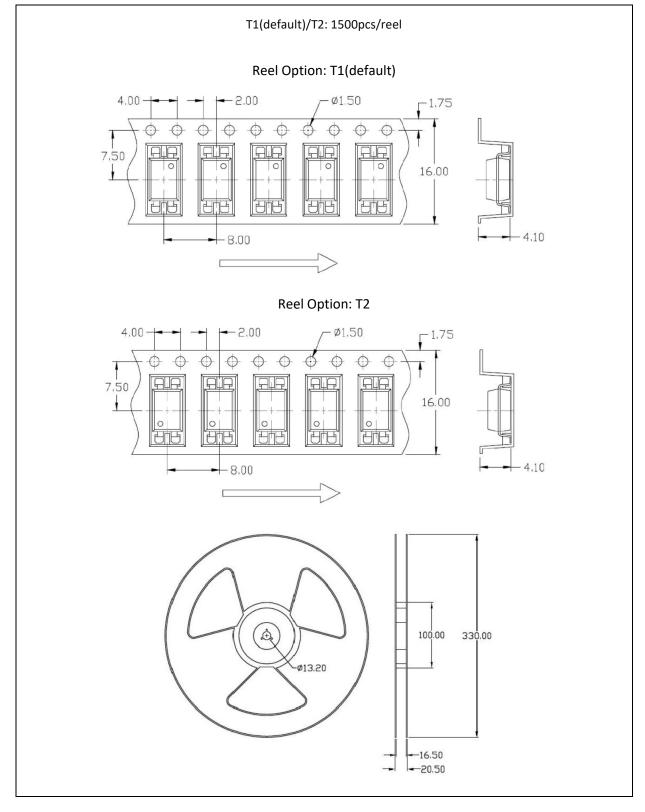
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).

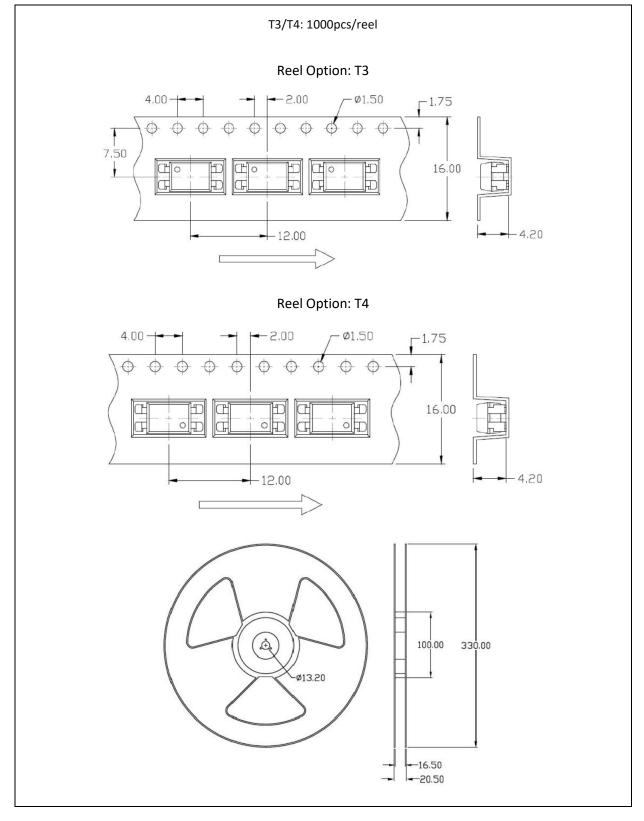


Reel Dimension:





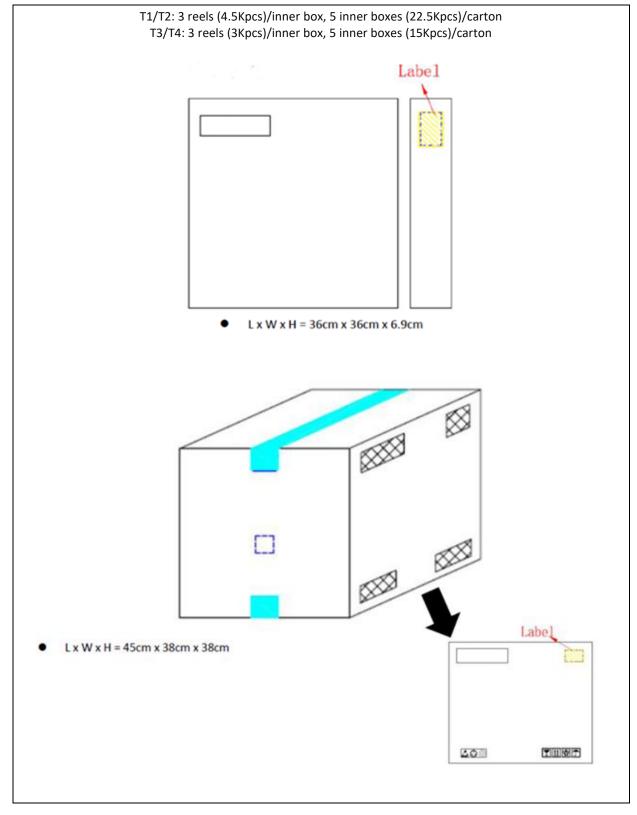
Reel Dimension:





PACKING SPECIFICATION:

Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

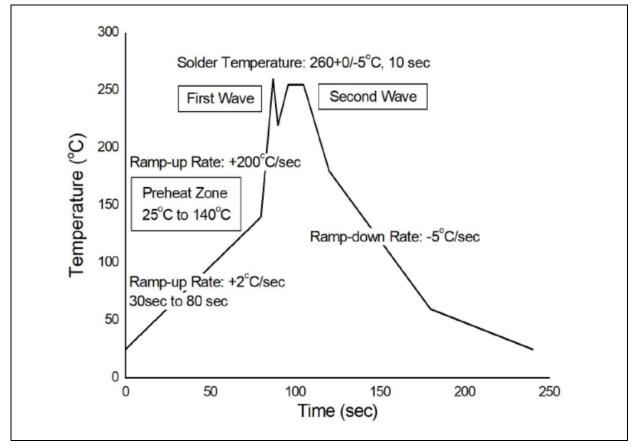
Г

| Supplier $T_p \ge$ | T _c T _c T _c -5°C | er $T_p \leq T_c$ User t_p |
|---|--|---|
| Tsmax Preheat Are | , | t _p → |
| ← Time 25°C to | | + |
| | Time ⇔ | ♥ Pb-Free Assembly Profile |
| Profile Feature | | Pb-Free Assembly Profile 150°C |
| Profile Feature Temperature Min. (T _{smin}) | Time → Sn-Pb Assembly Profile | Pb-Free Assembly Profile |
| Profile Feature | Time → Sn-Pb Assembly Profile 100°C | Pb-Free Assembly Profile 150°C |
| Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) | Time → Sn-Pb Assembly Profile 100°C 150°C | Pb-Free Assembly Profile 150°C 200°C |
| Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax}) | Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds | Pb-Free Assembly Profile 150°C 200°C 60-120 seconds |
| Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP) | Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. | Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. |
| Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL) | Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C | Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C |
| Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL) | Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds | Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds |
| Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tt to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)Peak Body Package Temperature | Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C | Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C |



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

| Soldering Temperature | 380±5°C |
|-----------------------|------------|
| Soldering Time | 3 sec max. |

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.